

 Package Material Content Declaration							
Package Description							
217-Ball, 15 x 15 x 1.4 mm, 0.80 mm Pitch, Low Profile Fine Pitch Ball Grid Array Package (LFBGA)							
Lead Finish		Package Code / GPC		ATB / CGF			
J-STD-609 Category		e8		Termination Base Alloy:		Laminate	
Package Material Declaration							
Material	Substance	CAS #	Weight (mg)	Homogeneous Material		Package	
				Percentage	ppm	Percentage	ppm
Integrated Circuit	Silicon (Si)	7440-21-3	12.582	100.0	1000000	2.88	28766
Sub-Total			12.582	100.0	1000000	2.88	28766
Die Attach	Silver (Ag)	7440-22-4	0.880	81.5	815000	0.20	2012
	Di-ester Resin	Proprietary	0.083	7.7	77000	0.02	190
	Functionalized Ester Resin	Proprietary	0.083	7.7	77000	0.02	190
	Polymeric Material	Proprietary	0.033	3.1	31000	0.01	77
Sub-Total			1.080	100.0	1000000	0.25	2469
Bond Wire	Copper (Cu)	7440-50-8	1.708	97.6	976000	0.39	3905
	Palladium (Pd)	7440-05-3	0.042	2.4	24000	0.01	96
Sub-Total			1.750	100.0	1000000	0.40	4001
Encapsulation	Silica Fused	60676-86-0	191.463	89.8	898000	43.77	437737
	Epoxy Resin	Proprietary	12.153	5.7	57000	2.78	27785
	Phenol Resin	Proprietary	8.955	4.2	42000	2.05	20473
	Carbon Black	1333-86-4	0.640	0.3	3000	0.15	1462
Sub-Total			213.211	100.0	1000000	48.75	487458
Laminate	Copper (Cu)	7440-50-8	62.788	41.7	417000	14.35	143550
	Filament Fiber Glass	65997-17-3	33.878	22.5	225000	7.75	77455
	BT Epoxy Resin	Proprietary	33.878	22.5	225000	7.75	77455
	Inorganic Filler	21645-51-2	20.026	13.3	133000	4.58	45784
Sub-Total			150.570	100.0	1000000	34.42	344244
Soldermask	Acrylate Resin	Proprietary	2.059	41.0	410000	0.47	4708
	Barium Sulfate	7727-43-7	1.612	32.1	321000	0.37	3686
	Epoxy Resin	Proprietary	0.804	16.0	160000	0.18	1837
	Organic Compounds	Proprietary	0.357	7.1	71000	0.08	815
	Talc	14807-96-6	0.141	2.8	28000	0.03	321
	Silica	7631-86-9	0.035	0.7	7000	0.01	80
	Phthalocyanine Blue	147-14-8	0.015	0.3	3000	0.00	34
Sub-Total			5.022	100.0	1000000	1.15	11482
Solder Ball	Tin (Sn)	7440-31-5	52.380	98.5	985000	11.98	119755
	Silver (Ag)	7440-22-4	0.532	1.0	10000	0.12	1216
	Copper (Cu)	7440-50-8	0.266	0.5	5000	0.06	608
Sub-Total			53.178	100.0	1000000	12.16	121579
Total			437.393			100.00	1000000

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero).

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at <http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/>.

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <http://echa.europa.eu/web/guest/candidate-list-table>.